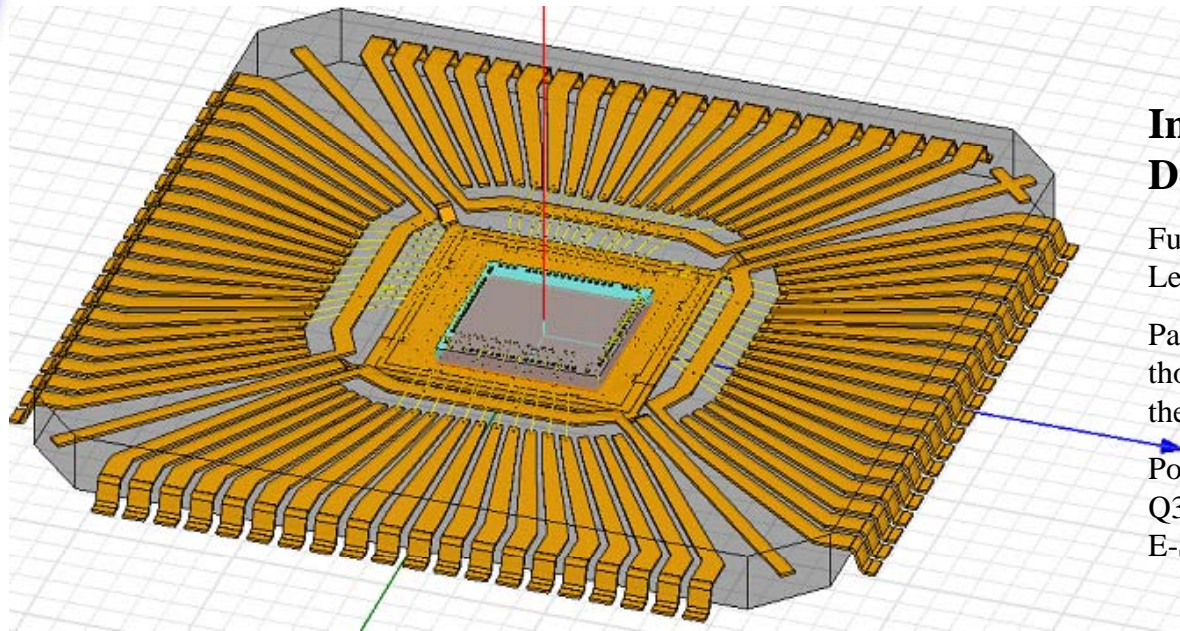




Electrical and Thermal / Mechanical Simulation Models of Lead Frames and Stacked Substrates including TSV Dies and Interposers

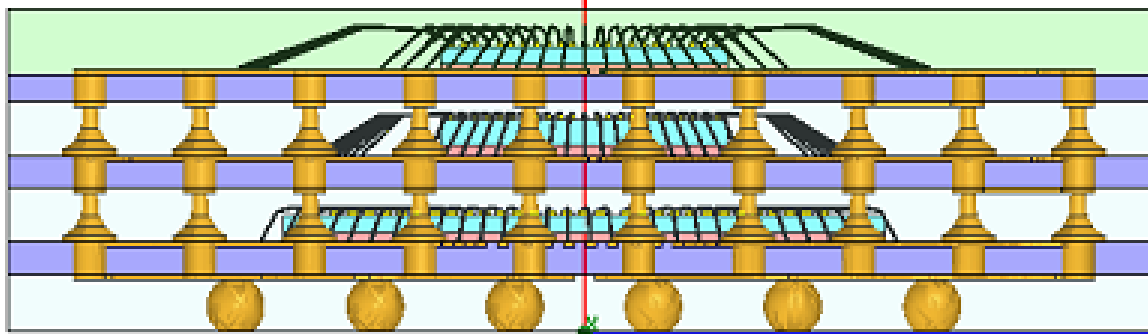


Intelligent Lead Frame Design

Full Design and Parametric Editing of all Lead Frame types.

Parametric optimizer simultaneously modifies thousands of features to automatically reduce the total bond wire length to save gold.

Ports Analysis Models to Ansoft's HFSS and Q3D, CSTs Microwave Studio and E-System Design's Sphinx & Sphinx 3DXT



Unlimited stacking of any TSV die, substrate or PCB to configure complete packages or test and analysis systems.

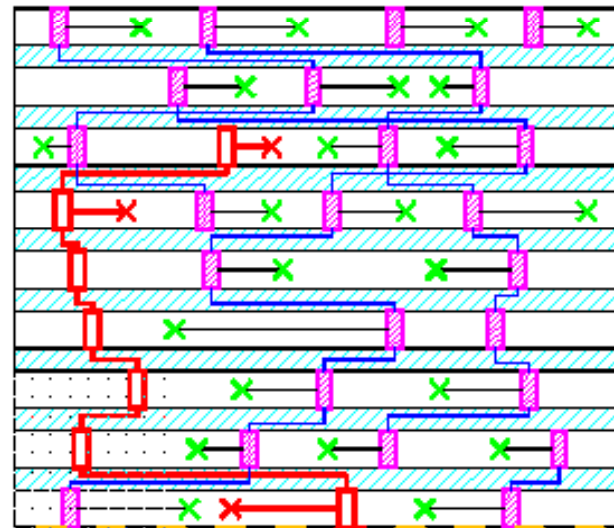
Ports Analysis Models to Ansoft's HFSS and Q3D, CSTs Microwave Studio and E-System Design's Sphinx & Sphinx 3DXT

TSV Dies Stacked with Interposers on a Flip Chip Substrate

Red Net is a Sample of a Net Being Analyzed

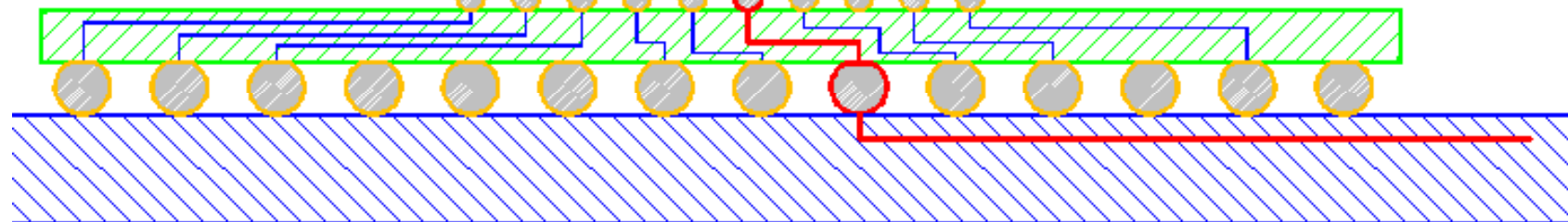
Links to Analysis:

- E-System Design's Sphinx & Sphinx 3DEXT
- Ansoft's HFSS
- Ansoft's Q3D
- CST's Microwave Studio



Possible Simulation Models:

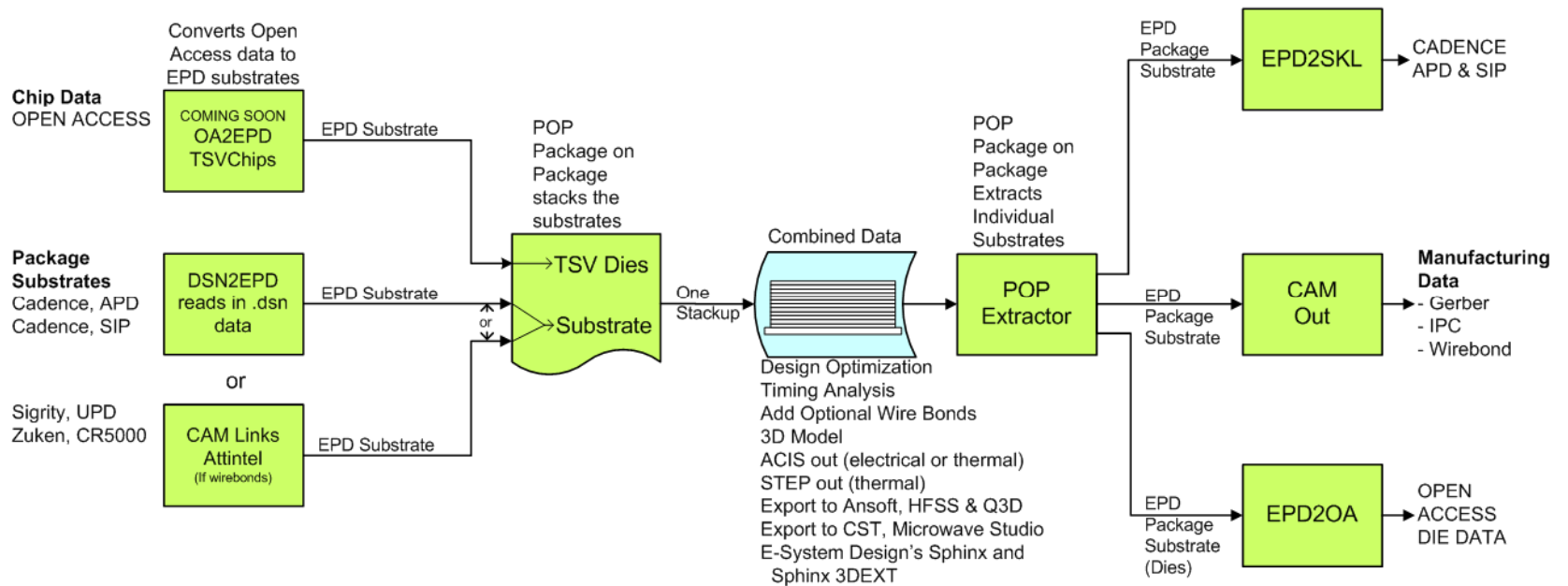
- TSV Wafer with Probes / Probe Head and Probe PCB
- Stacked TSV Dies and Package
- Stacked TSV Dies and Package with Evaluation PCB
- Stacked TSV Dies and Package in Test Socket on Test PCB



TSV
 Active Electronics Begins
 Thickness is Exaggerated



Data Flow



CAD Design Software

A Division of CAD Design Services, Inc. Founded in 1989

2975 Bowers Ave. Suite 315

Santa Clara, CA 95051

408-436-1340 www.CAD-Design.com